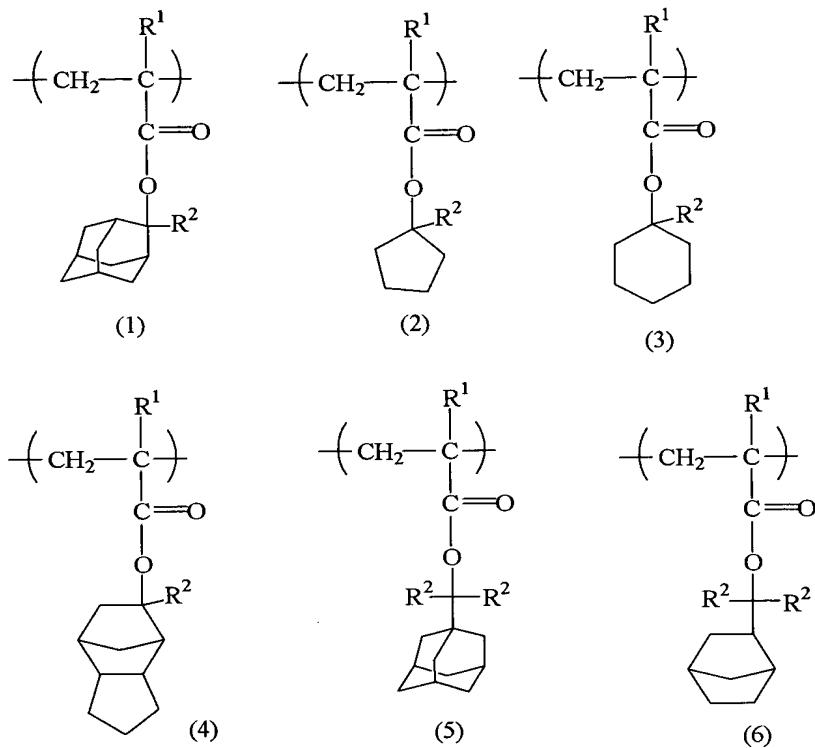


ABSTRACT OF THE DISCLOSURE

A radiation-sensitive resin composition comprising (A) a resin comprising at least two recurring units of the formulas (1)-(6) in the total amount of 5-70 mol%, but each in the amount 5 of 1-49 mol%, the resin being insoluble or scarcely soluble in alkali, but becoming easily soluble in alkali by the action of an acid, and (B) a photoacid generator.



wherein R¹ is a hydrogen or methyl and R² is a substituted or
10 unsubstituted alkyl group having 1-4 carbon atoms. The resin
composition is useful as a chemically amplified resist having
high transmittance of radiation, sensitivity, resolution, dry
etching resistance, and pattern profile.